

LF 1608 Series

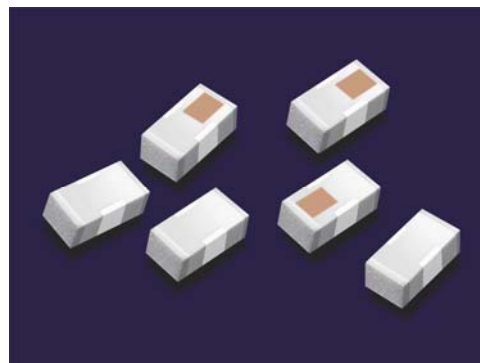
Multilayer Chip Low-Pass Filters

Features

- ❖ Ultra small SMD type with low loss at pass-band and high attenuation at stop-band.
- ❖ HF & RoHS compliant.

Applications

- ❖ 0.8 ~ 6 GHz wireless communication systems, including DECT/PACS/PHS/GSM/DCS phones, WLAN card, Bluetooth modules, Hyper-LAN, etc.



Specifications

Part Number	Frequency Range (MHz)	Insertion Loss @ BW(dB)	Return Loss @ BW(dB)	Frequency	Attenuation (dB)
LF1608-A5R5EAA_	4900 ~ 5950	0.7 max. @ 25 °C	12 min.	9800MHz	20 min.
		0.9 max. @ -40~105 °C		11900MHz	30 min.

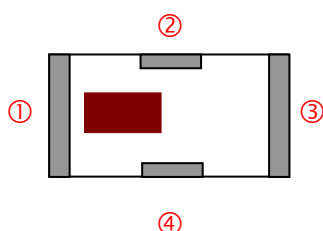
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +105 °C
 Storage Temperature Range : -40 ~ +105 °C
 Storage Period : 12 months max.
 Power Capacity : 3W max.

Part Number

LF 1608 - A 5R5 EAA □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	LF : Band-Pass Filter	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	A	④ Frequency Range	5R5=5500MHz
⑤ Specification Code	EAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

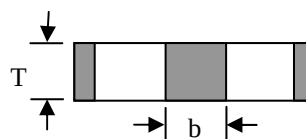
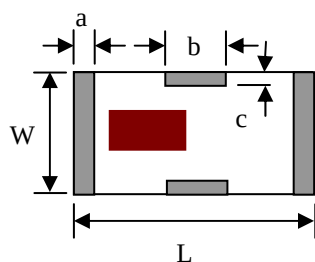
Terminal Configuration



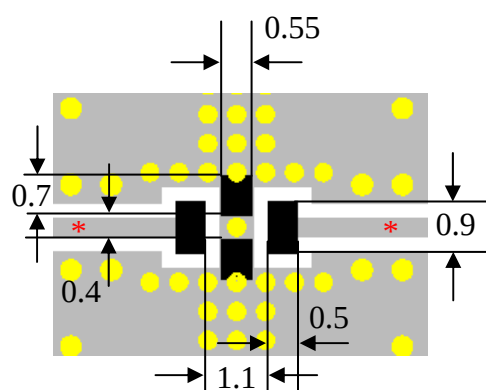
No.	Terminal Name	No.	Terminal Name
①	IN	③	OUT
②	GND	④	GND

Dimensions and Recommended PC Board Pattern

Unit : mm



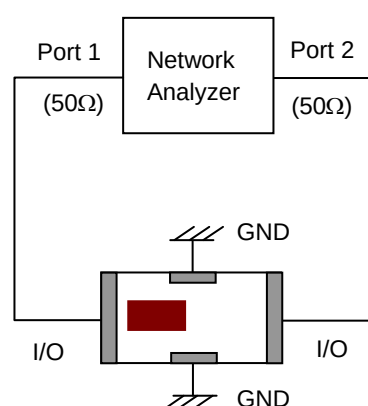
Mark	L	W	T	a	b	c
Dimensions	1.6 ± 0.10	0.8 ± 0.10	0.6 ± 0.10	0.2 ± 0.1	0.5 ± 0.1	0.15 ± 0.10



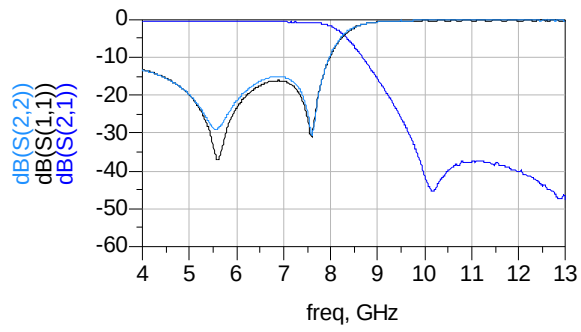
-  Solder Resist
-  Land
-  Through-hole (φ 0.3)

* Line width should be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

Measuring Diagram



Electrical Characteristics (T=25°C)

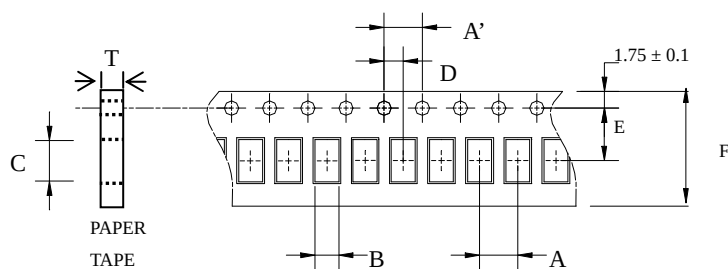


Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

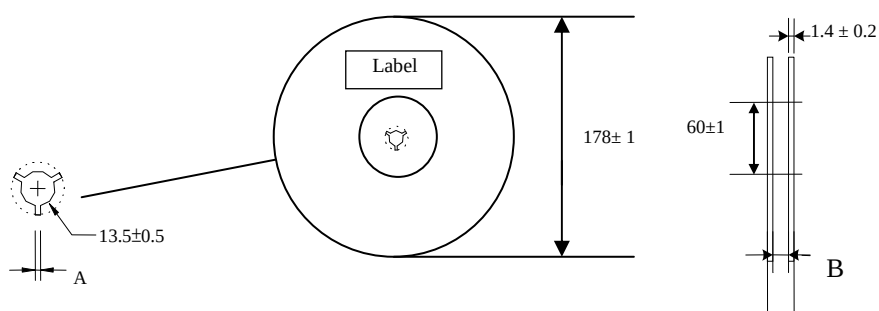
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



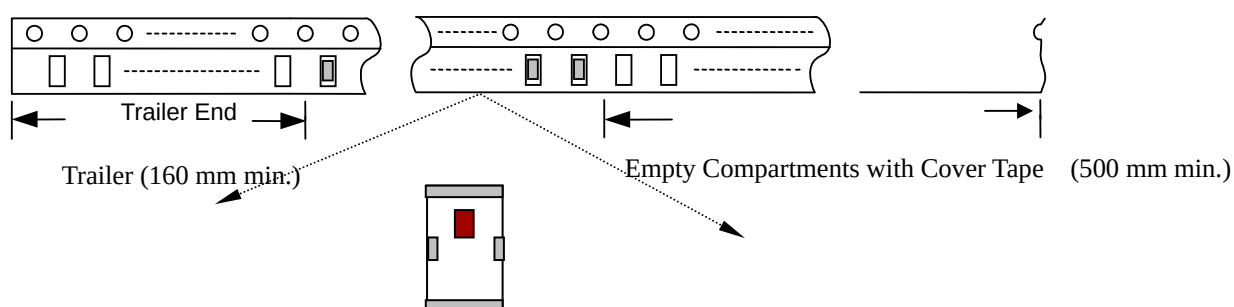
Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0± 0.1	4.0± 0.1	1.10± 0.1	1.92± 0.1	2.0± 0.1	3.5± 0.1	8.0± 0.1	0.75± 0.05	4,000pcs	Paper

❖Reel Dimensions (Unit: mm)

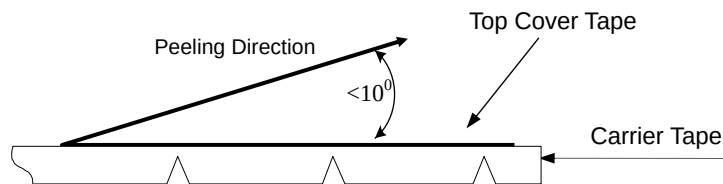


Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape



❖ Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

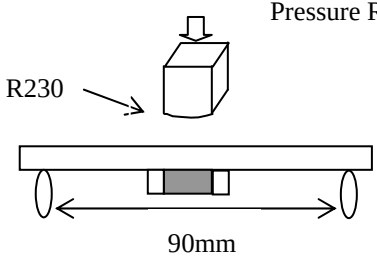
❖ Storage Conditions

- (1) Temperature: 15 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.
- (3) Products are proposed to used within six months of receipt.

Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

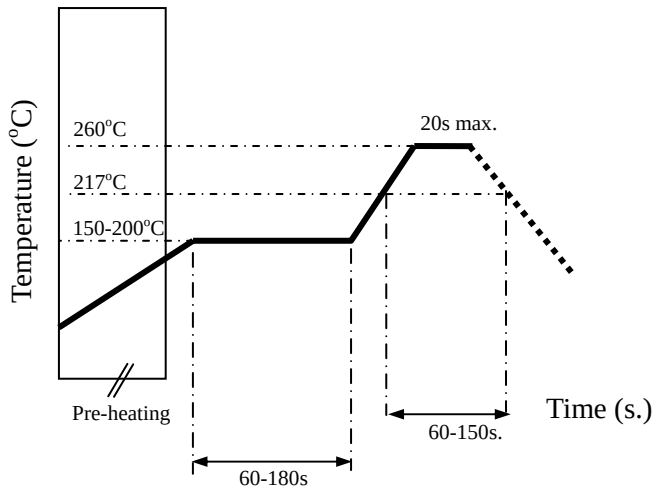
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 10N minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 1.6mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection. 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery: 1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40 \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



Notes

- ❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

Advanced Ceramic X Corp.

No.165 Hanyang Road, Hsinchu Industrial District, Hsinchu Hsien, Taiwan, 30350

TEL: 886-3-5987008 FAX: 886-3-5987001

E-mail: acx@acxc.com.tw

<http://www.acxc.com.tw>